/ Descriptions

VRW056 Ṃ Ṃ Ł SQS Æ Ṁ ч s ‖ ˥ Silicon PNP transistor in a SOT-23 Plastic Package.

/ Features

` ⅵ Э я ⅹ ı ت ⁼ я ∪ Ц/ѣ 5VG4 : ; 5N Й ´

High breakdown, low $V_{CE(sat)}$,complements the 2SD1782K.

/ Applications

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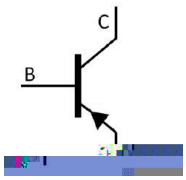
Medium power amplifier applications.

/ Equivalent Circuit



/ Pinning



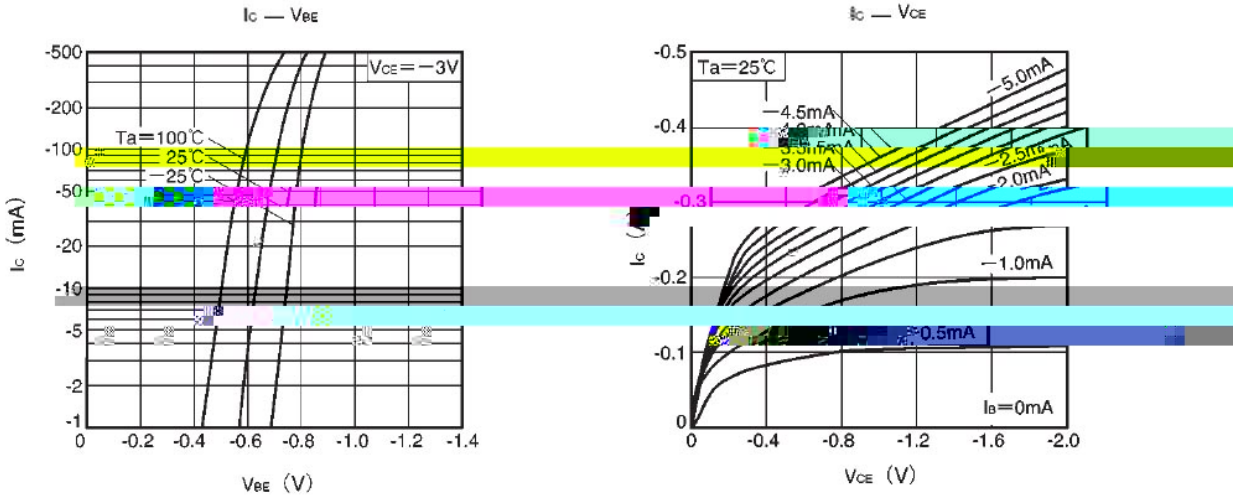
PIN1 χ Base PIN 2 χ Emitter PIN 3 χ Collector

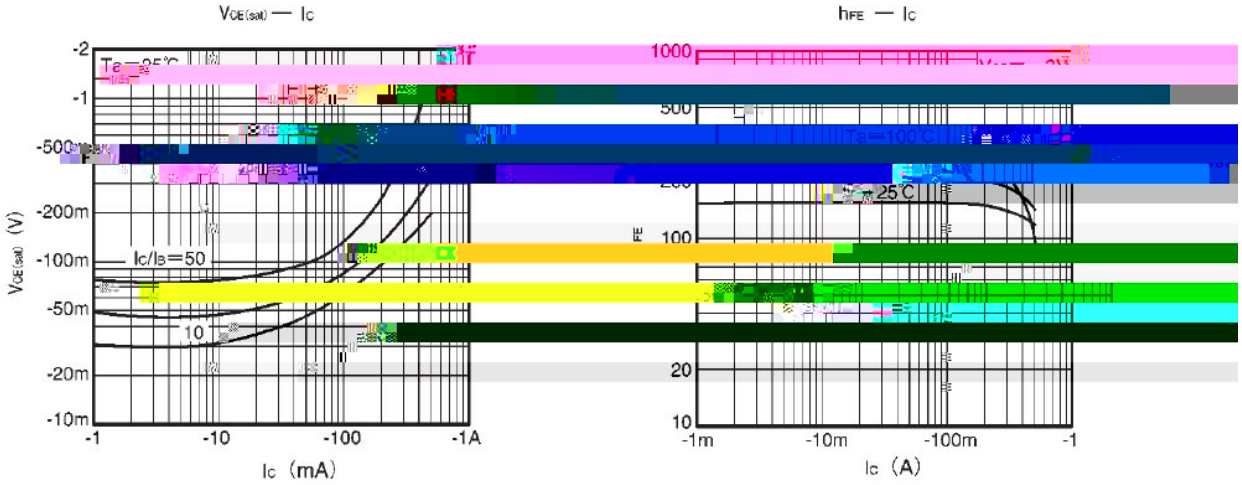
/ h_{FE} Classifications & Marking

h_{FE} Classifications Symbol	Q	R
h_{FE} Range	120~270	180~390
Marking	HAKQ	HAKR

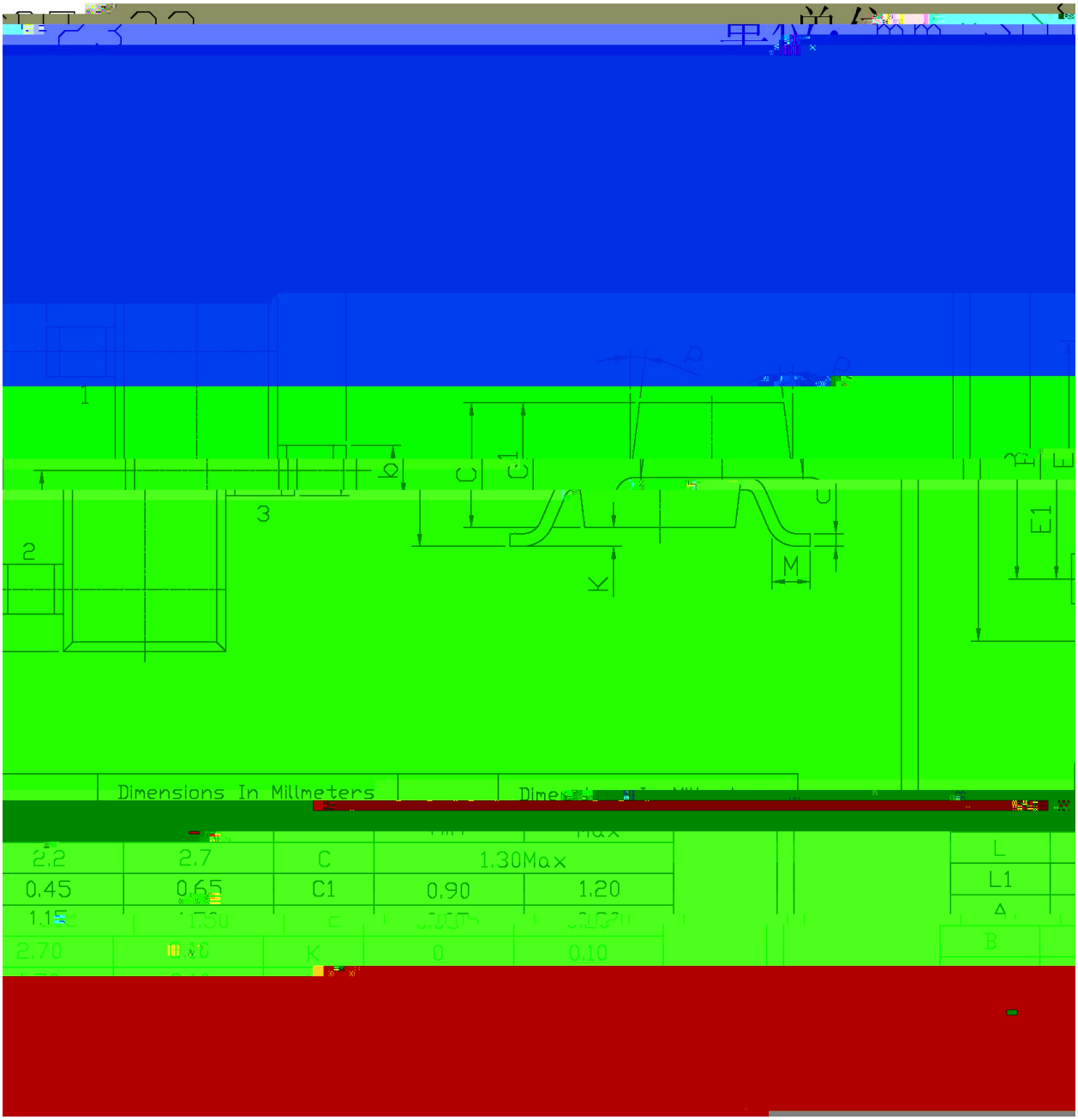
v ̈Ω̣ Parameter	ϟ N Symbol	̈Ω̣ Ö Rating	D Ӈ Unit
Collector to Base Voltage	V_{CBO}	-80	V
Collector to Emitter Voltage	V_{CEO}	-80	V
Emitter to Base Voltage	V_{EBO}	-5	V
Collector Current - Continuous	I_C	-500	mA
Collector Power Dissipation	P_C	200	mW
Junction Temperature	T_j	150	ɬ
Storage Temperature Range	T_{stg}	-55 Ḱ 150	ɬ

/ Electrical Characteristic Curve





/ Package Dimensions



/ Marking Instructions



ب ˝ χ

K χ ⌘ ʒ ᴵ Ɱ

DN χ ⌘ ʒ ᴺ Ɱ

U χ ⌘ h_{FE} ‘ ᶠ Ɱ

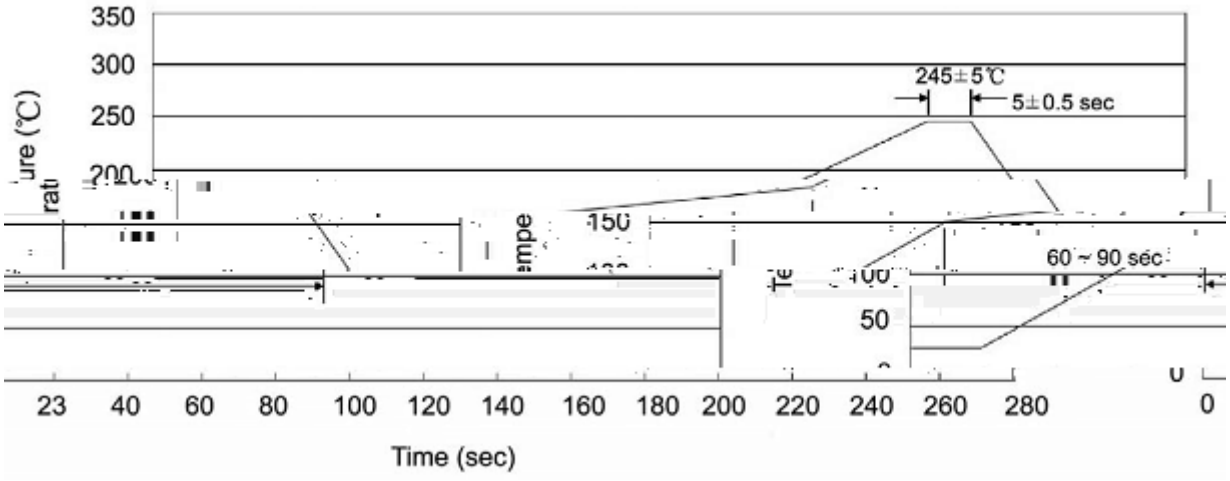
Note:

H: Company Code

AK: Product Type Code

R: h_{FE} Classifications Symbol Code

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



ب ˝ χ

1 ⺊ ♬ □ ỷ 25 Ḱ 150 ɫ ı `H ڑ 60 Ḱ 90sec;

2 Š Ö □ ỷ 245 ° 5 ɫ ı `H ڑ ˋY ⺈ ⺮ 5 ° 0.5sec;

3 ì ˙ ⺈ ˛ ɔ ⺌ ỷ ⺮ 2 Ḱ 10 ɫ /sec.

Note:

1.Preheating:25~150 ɫ , Time:60~90sec.

2.Peak Temp.:245 ° 5 ɫ , Duration:5 ° 0.5sec.

3. Cooling Speed: 2~10 ɫ /sec.

/ Resistance to Soldering Heat Test Conditions

□ ỷ χ 260 ° 5 ɫ `H ڑ χ 10 ° 1 sec. Temp.:260 ° 5 ɫ Time:10 ° 1 sec

/ Packaging SPEC.

ɔ` γ ⺊ / REEL

Package Type	Units					Dimension (unit mm^3)		
	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box
SOT-23	3,000	10	30,000	6	180,000	7 ρ ×8	180×120×180	390×385×205

/ Notices